



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-08-03
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STP30N65M5	R1DZ*M5F6B52	A	SHENZHEN B/E	2016-08-03
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.1-4.5	3	THROUGH HOLE	
Comment	TO 220 AB NON ISOL			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	R1DZ*MSF6852					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	15.956	mg	supplier	die	Silicon (Si)	7440-21-3		14.815	mg	928491	7797
				supplier	metallization	Aluminium (Al)	7429-90-5		0.276	mg	17298	145
				supplier	metallization	Titanium (Ti)	7440-32-6		0.010	mg	627	5
				supplier	metallization	Nickel (Ni)	7440-02-0		0.606	mg	37979	319
				supplier	metallization	Silver (Ag)	7440-22-4		0.036	mg	2256	19
				supplier	Passivation	Silicon Nitride	12033-89-5		0.064	mg	4011	34
				supplier	Passivation	Silicon Oxide	7631-86-9		0.005	mg	313	3
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.007	mg	439	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.101	mg	6330	53
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.036	mg	2256	19
Leadframe	Copper & its alloys	1259.453	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.376	mg	993587	658619
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	994	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	299	198
				supplier	metallization	Nickel (Ni)	7440-02-0		6.408	mg	5088	3373
				supplier	metallization	Phosphorus (P)	12185-10-3		0.040	mg	32	21
Soft solder	Solder	13.732	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	13.114	mg	954996	6902
				supplier	solder	Silver (Ag)	7440-22-4		0.343	mg	24978	181
				supplier	solder	Tin (Sn)	7440-31-5		0.275	mg	20026	145
Bonding wires	Other inorganic materials	0.147	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.146	mg	995228	77
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	4772	0
Bonding Ribbons	Other Nonferrous metals & alloys	1.212	mg	supplier	Ribbon	Aluminium (Al)	7429-90-5		1.212	mg	1000000	638
				supplier	mold compound	Silica, vitreous	60676-86-0		524.730	mg	870000	276174
Encapsulation	Other Organic Materials	603.138	mg	supplier	mold compound	Epoxy resin	25068-38-6		60.314	mg	100000	31744
				supplier	mold compound	Phenol resin	29690-82-2		15.078	mg	24999	7936
				supplier	mold compound	Carbon Black	1333-86-4		3.016	mg	5001	1587
Connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348